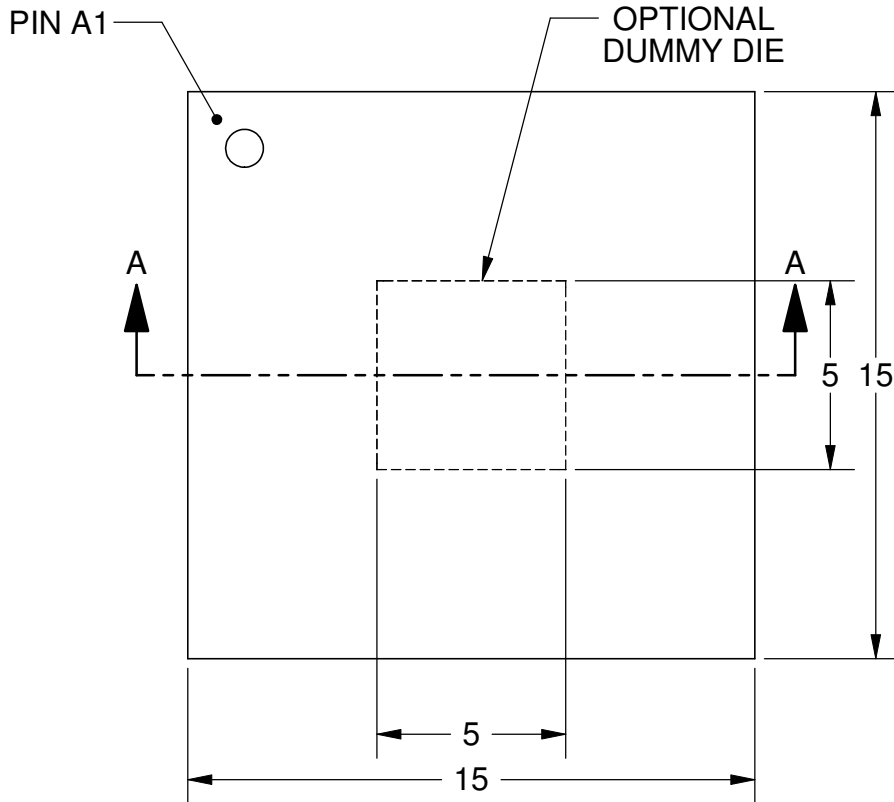
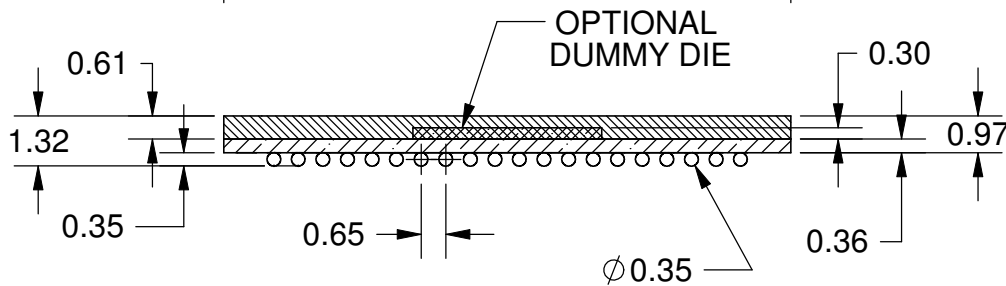
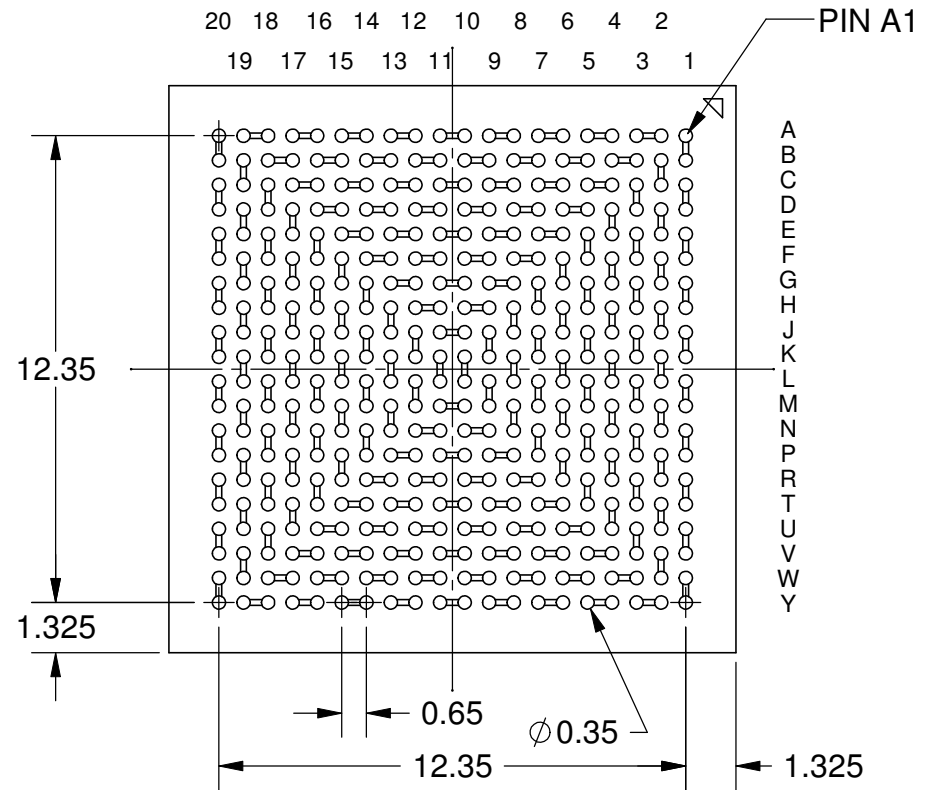


REVISIONS				
DATE	REV.	ECO	DESCRIPTION	APPROVED

TOP VIEW



BALL VIEW


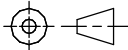


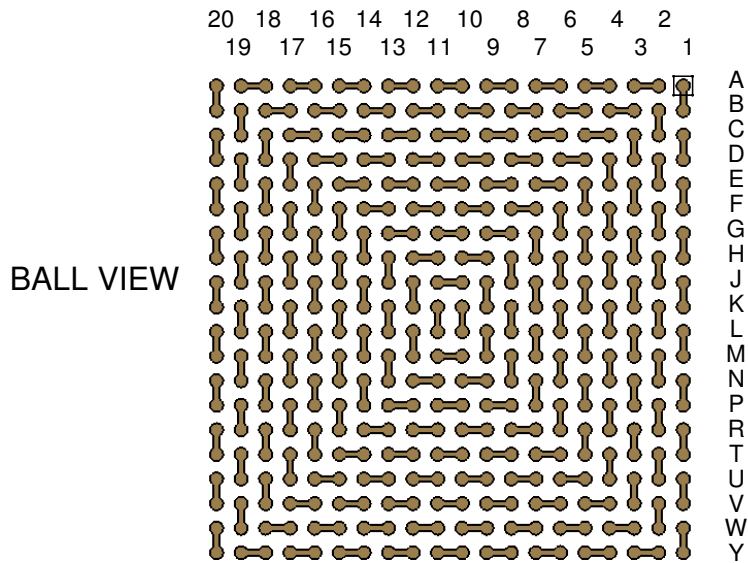
SECTION A-A

Notes: (Unless Otherwise Specified).

- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
- 3) BALL DIAMETER (BEFORE REFLOW): 0.35mm.
- 4) SOLDER MASK DEFINED PAD OPENING: 0.33mm.
- 5) PAD Cu DIAMETER: 0.457mm.
- 6) SUBSTRATE MATERIAL: BT (ALTERNATE FR4).
- 7) DUMMY DIE IS OPTIONAL.
- 8) DAISY CHAIN PATTERN (SEE PAGE 2).
- 9) MSL-3 RECOMMEND BAKING 24 HOURS @ 125C TO REMOVE MOISTURE PRIOR TO SOLDERING TO PC BOARD.

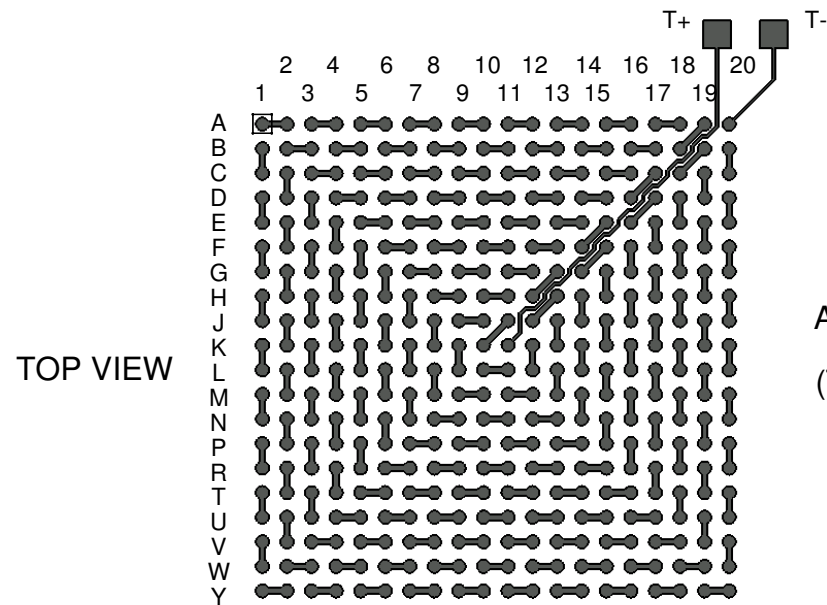
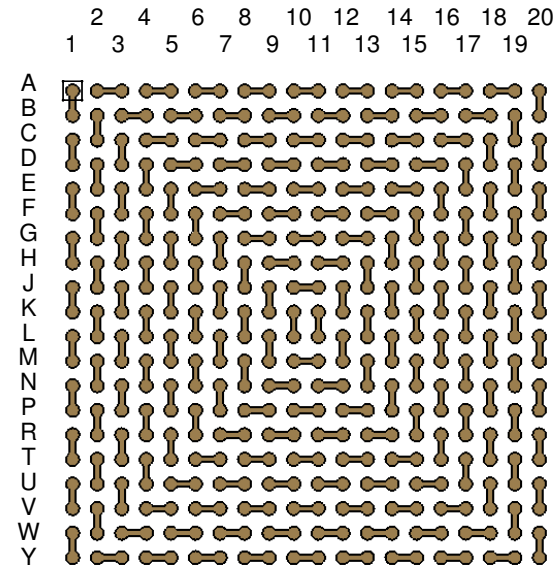
PART NUMBER TABLE				
PART NUMBER	BALL ALLOY	Pb-FREE	RoHS	Si DIE
BGA400T.65C-DC209	Sn96.5/Ag3.0/Cu0.5	YES	YES	NO
BGA400T.65C-DC209D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES
BGA400T.65-DC209	Sn63/Pb37	NO	NO	NO
BGA400T.65-DC209D	Sn63/Pb37	NO	NO	YES

TOLERANCE UNLESS NOTED		APPROVALS		DATE				
X.XX	+/- 0.01	DRAWN	J. Hines	8/6/2010				
X.XXX	+/- 0.005	ENG						
X.XXXX	+/- 0.0005	MFG			SCALE	SIZE	DRAWING NO.	REV
ANGLES +/- 0.5° ALL DIMENSIONS IN <input type="checkbox"/> INCHES <input checked="" type="checkbox"/> MILLIMETERS		QA			5:1	A	515322	A
THIRD ANGLE PROJECTION 		CUST			DO NOT SCALE DRAWING		SHEET 1 OF 2	
		REVISED						



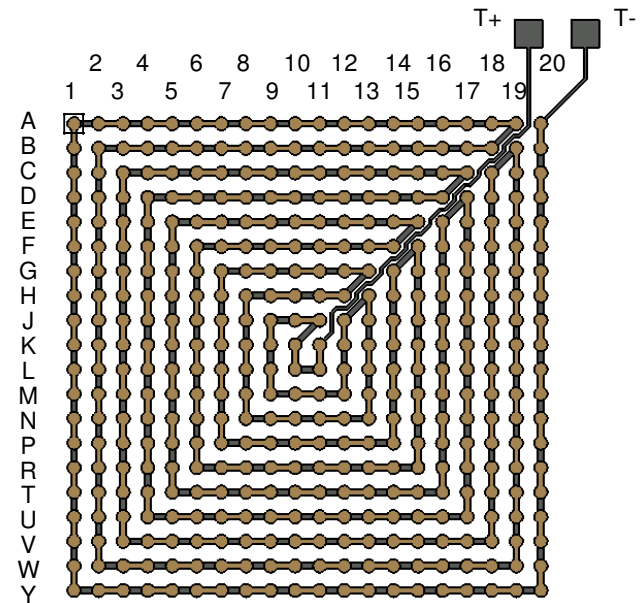
BALL VIEW

BOTTOM SIDE
(TOP X-RAY VIEW)



TOP VIEW

AFTER MOUNTING
TO TEST BOARD
(TOP X-RAY VIEW)



TEST VEHICLE BOARD

Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.457mm (18mil).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.152mm (6mil).
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING 0.33mm (13mil).

TopLine ®			
TITLE		BGA400T.65-DC209 DAISY CHAIN DUMMY	
SCALE	SIZE	DRAWING NO.	REV
5:1	A	515322	A
DO NOT SCALE DRAWING			SHEET 2 OF 2